

Please amend the Abstract on page 10 as follows:

~~APPARATUS FOR AND METHOD OF MANUFACTURE OF AN ELECTRONIC
ASSEMBLY~~

Abstract of the Disclosure

~~The assembly of surface mount components (SMCs) upon a printed circuit board (PCB) substrate is hindered by the limited space available upon the PCB due to the requirement of two solder pads per assembled component and by a process known as tombstoning where one end of an SMC may become dislocated from the PCB during the assembly process causing broken electrical connections between the solder pads and therefore inoperability of the PCB. The present invention therefore provides an electronic assembly (8) wherein the components are mounted substantially perpendicular to a PCB upon a single conductive region (12) and comprise means (18, 20) for connecting the component (10) to a neighbouring electrical device (24).~~

~~(Figure 1)~~ A method of manufacture of an electronic assembly that has a circuit board and an electrical component includes laying a first terminal of the electrical component upon a conductive region of the circuit board, providing solder paste contacting the first terminal of the component and the circuit board, and heating the solder paste so as to liquefy the solder paste thereby permitting a second terminal of the component to rise above the first terminal so as to erect the component substantially perpendicular to the conductive region. The method further includes curing the liquefied solder paste in order to fix the first

terminal of the component to the conductive region of
the circuit board.